

FIG. 1

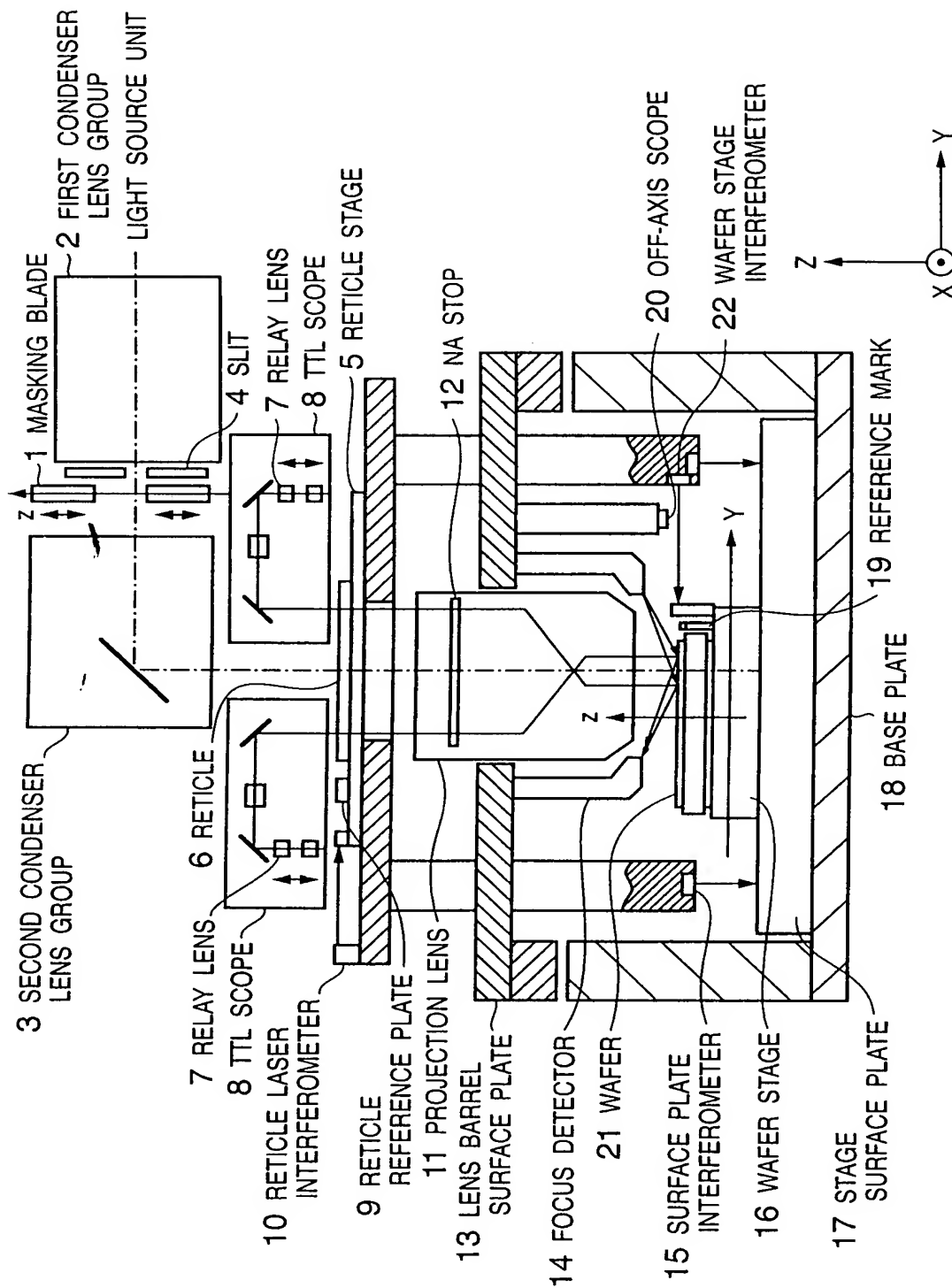
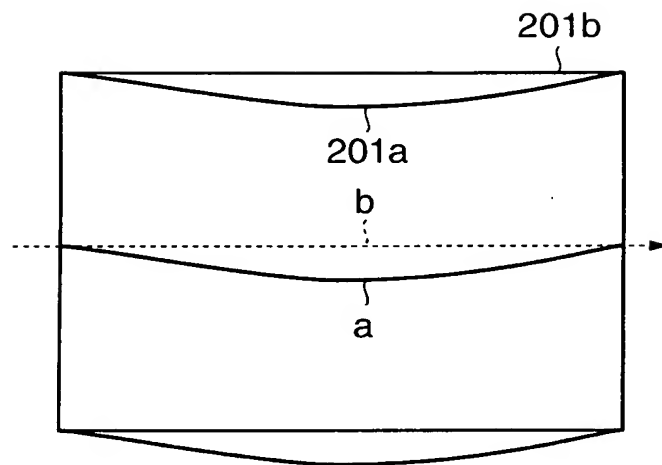


FIG. 2



20870* T850500T

10050581.011802

FIG. 3

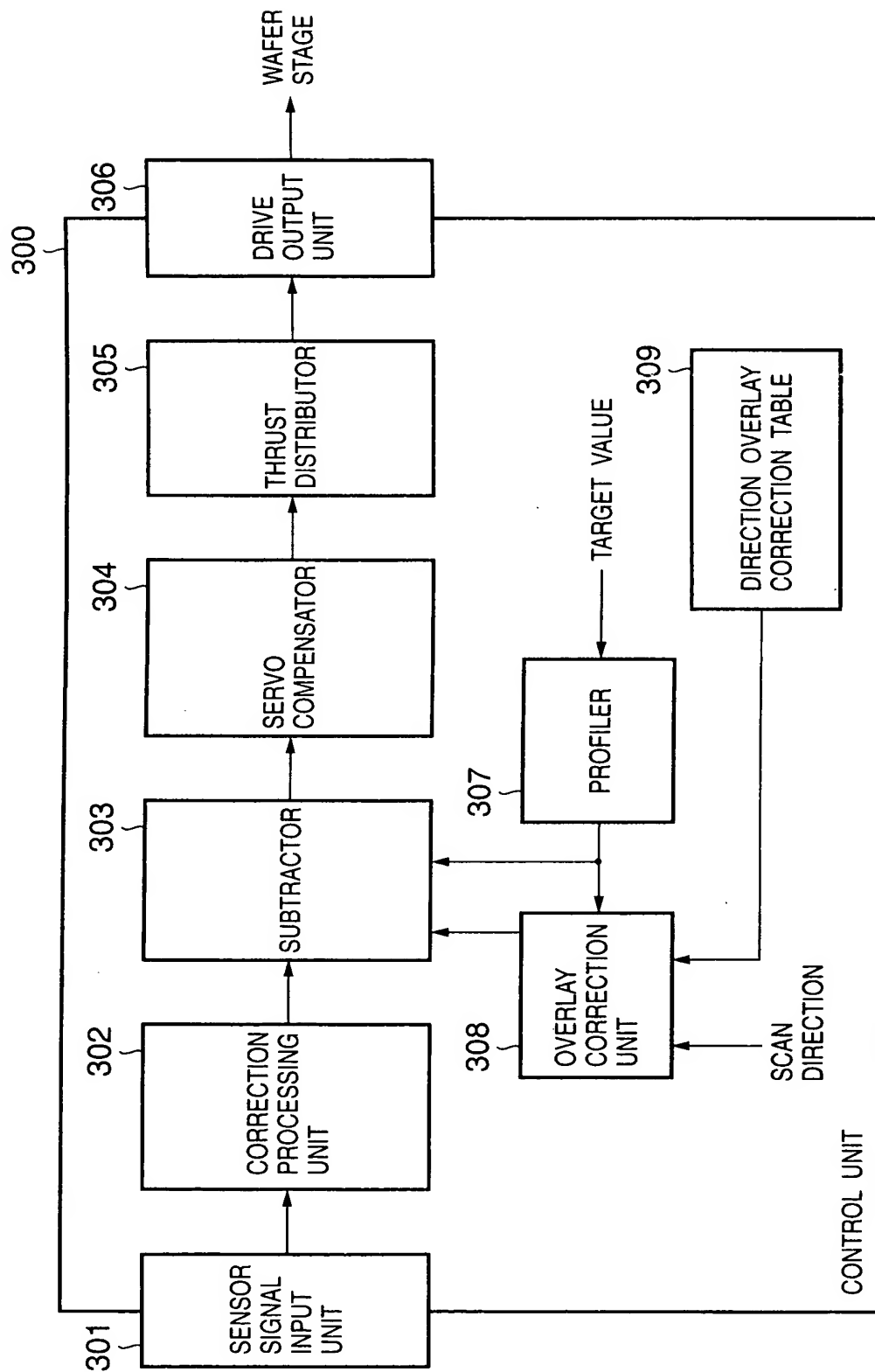


FIG. 4

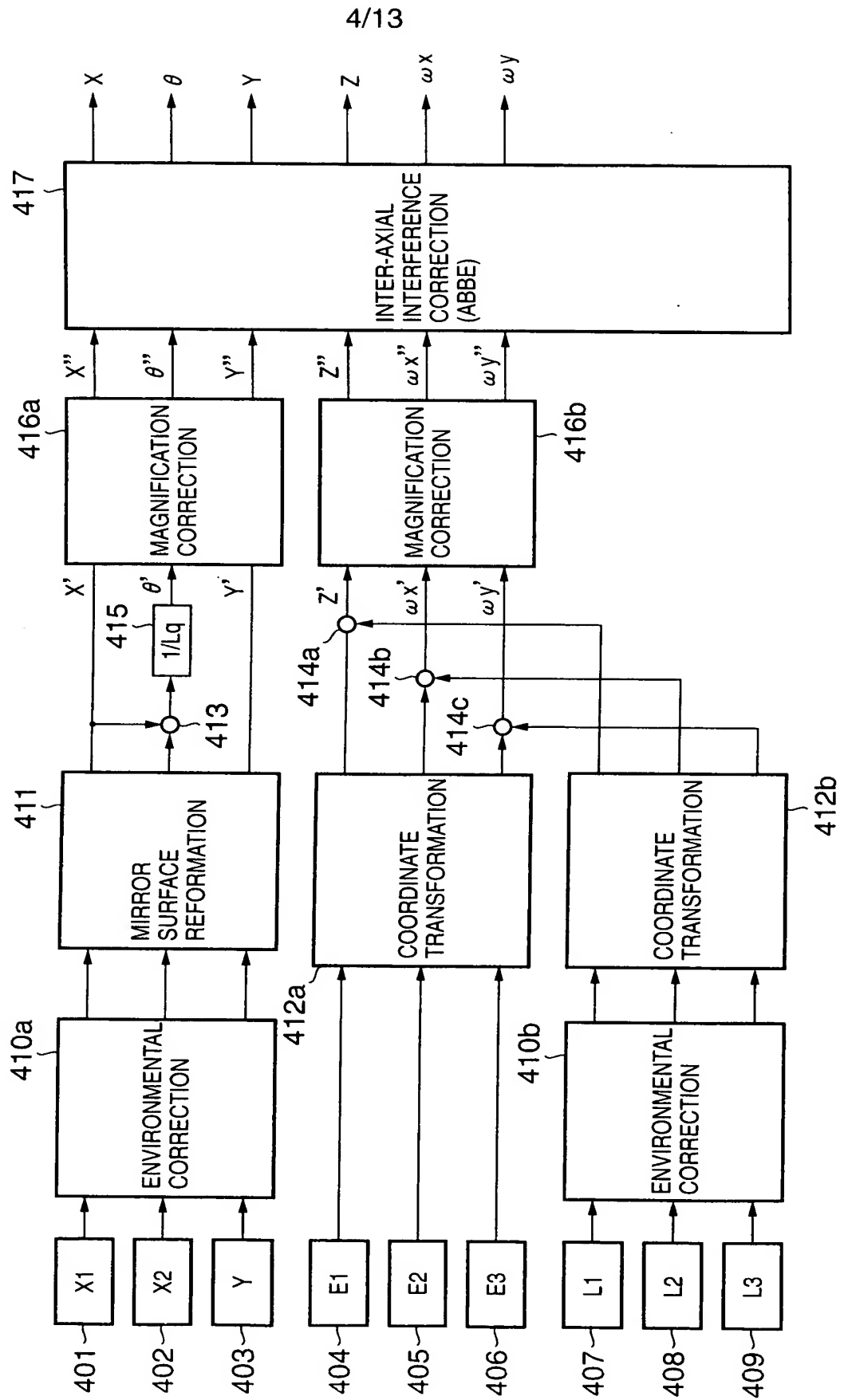


FIG. 5

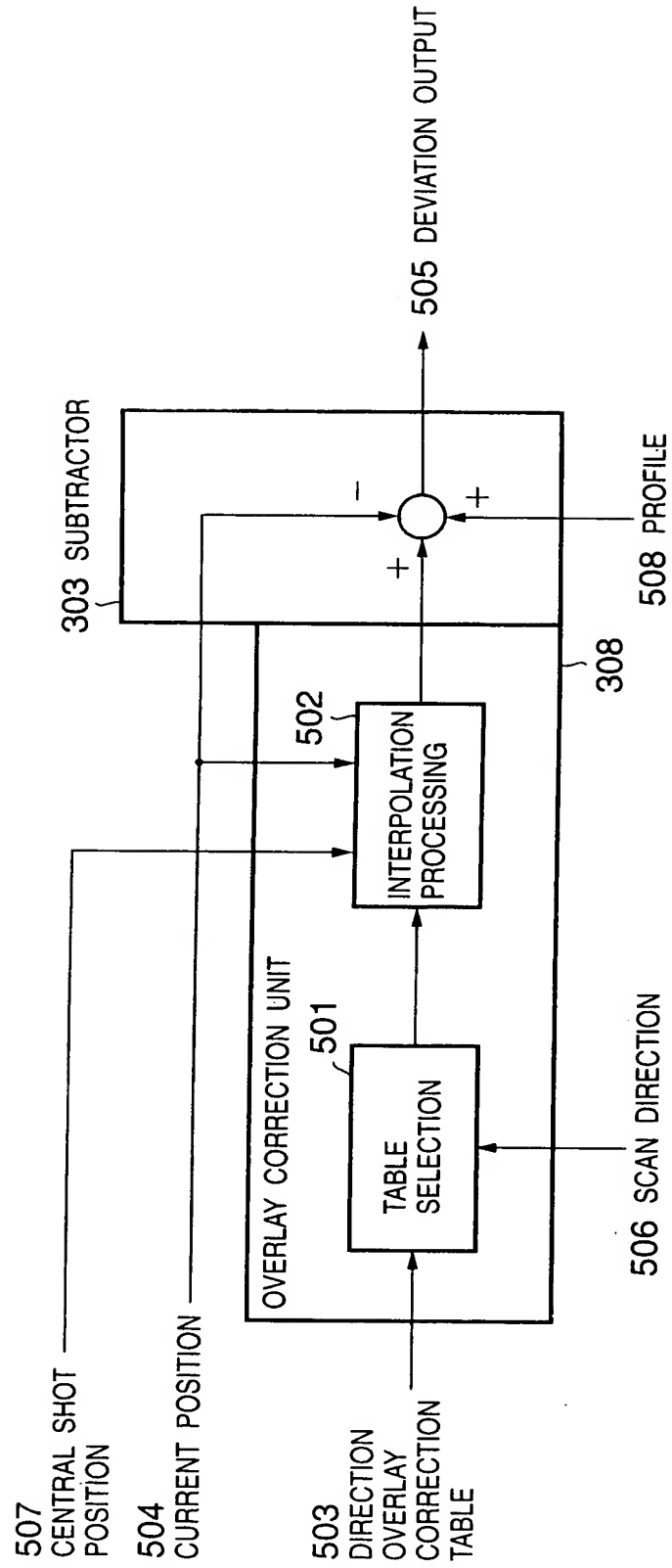


FIG. 6

ORIGIN INTERVAL			-16.000 4.000	[mm] [mm]		
CORRECTION DATA (FORWARD)				[nm/ppb]		
X	Y	Z	Qx	Qy	Qz	
5	1	10	0	-10	20	
4	1	8	10	-10	10	
2	0	10	20	20	10	
1	-1	12	20	40	10	
-1	-4	13	20	30	0	
-4	-2	10	40	40	-10	
-3	-4	7	10	50	-30	
-6	-5	4	0	80	-30	
-12	-9	0	-20	60	-40	
(REVERSE)						
X	Y	Z	Qx	Qy	Qz	
4	0	9	10	-10	20	
2	0	6	0	0	10	
0	-1	11	10	10	10	
0	-1	11	20	30	20	
-3	-4	10	40	10	0	
-5	-3	9	20	40	-10	
-5	-4	6	20	60	-30	
-7	-5	4	10	100	-30	
-14	-9	-1	0	80	-30	

1.0050581.011802

FIG. 7

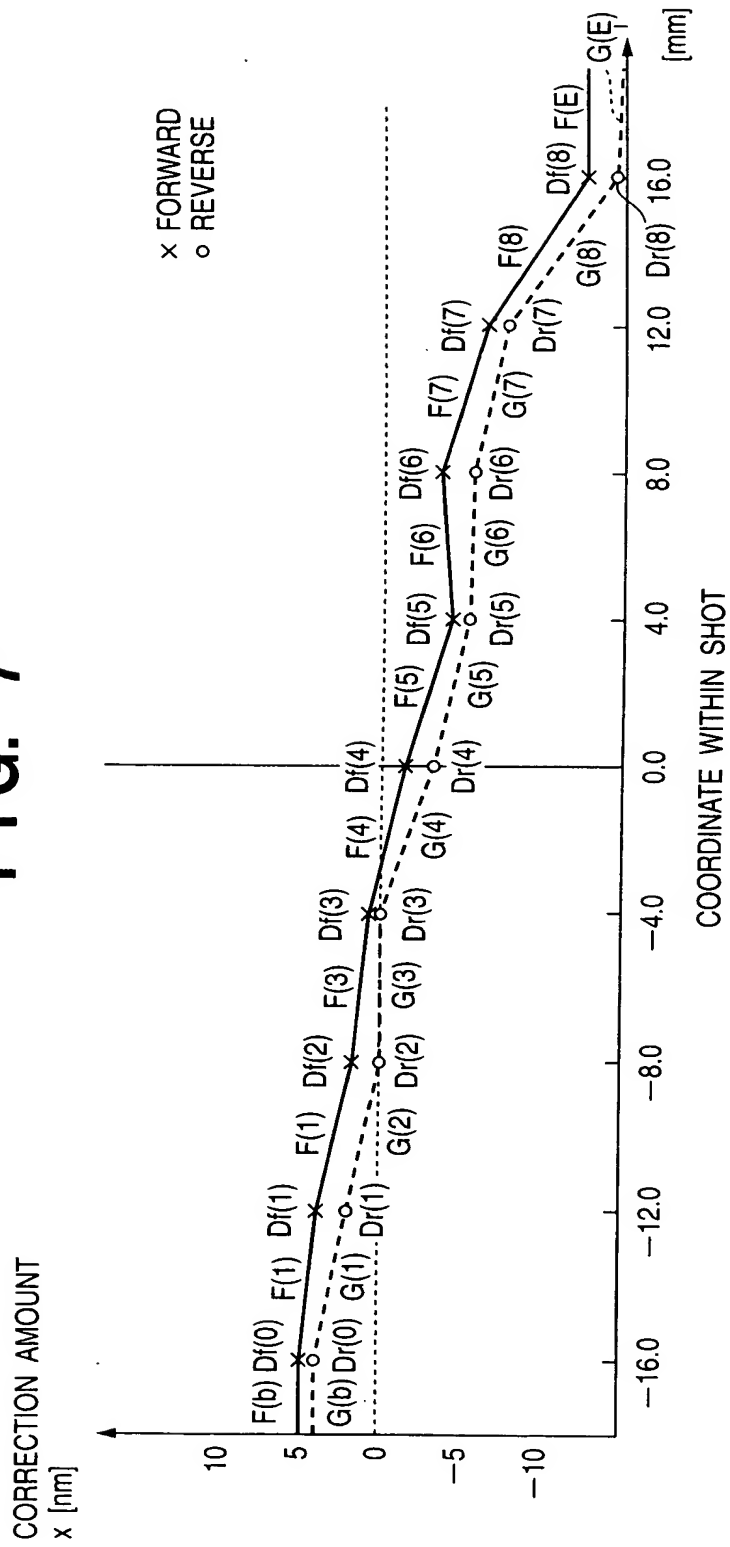



FIG. 8

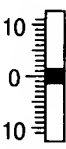
DIRECTION OVERLAY CORRECTION


ORIGIN
 INTERVAL

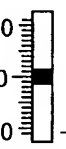
MAX NUMBER OF DATA


CORRECTION TABLE
 FORWARD :
 AXIS X



 DATA0



 DATA1



 DATA2

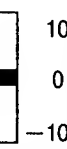

 DATA3



 DATA4



 DATA5



 DATA6



 DATA7



 DATA8



 DATA9



 DATA10



 DATA11

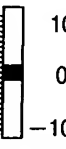

 DATA12

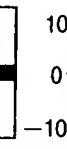

 DATA13



 DATA14


 DATA15

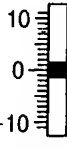

 DATA16



 DATA17



 DATA18



 DATA19


AXIS X



 DATA0



 DATA1

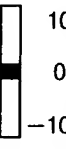

 DATA2

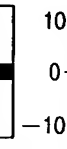

 DATA3



 DATA4


 DATA5


 DATA6


 DATA7


 DATA8


 DATA9

1001

10050581.01802

FIG. 9

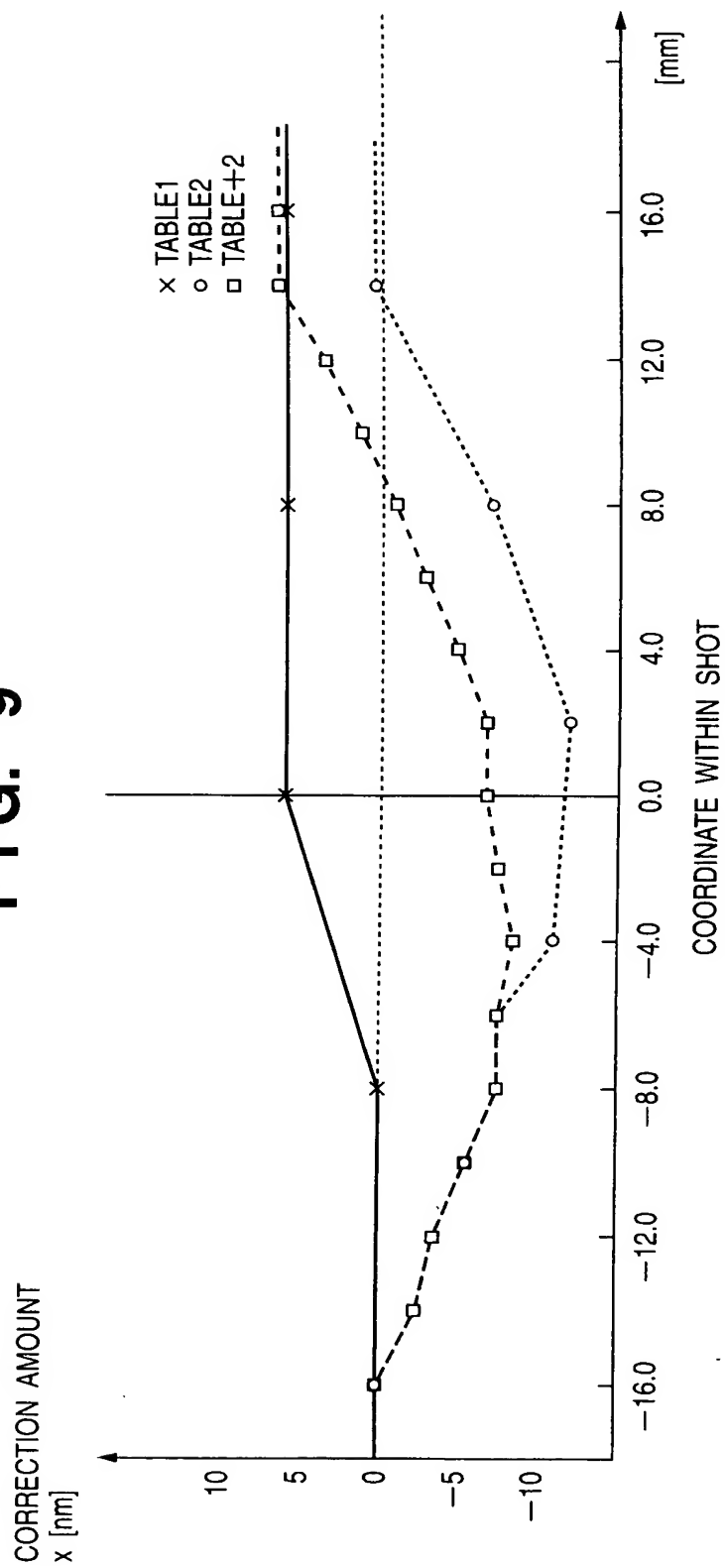


FIG. 10

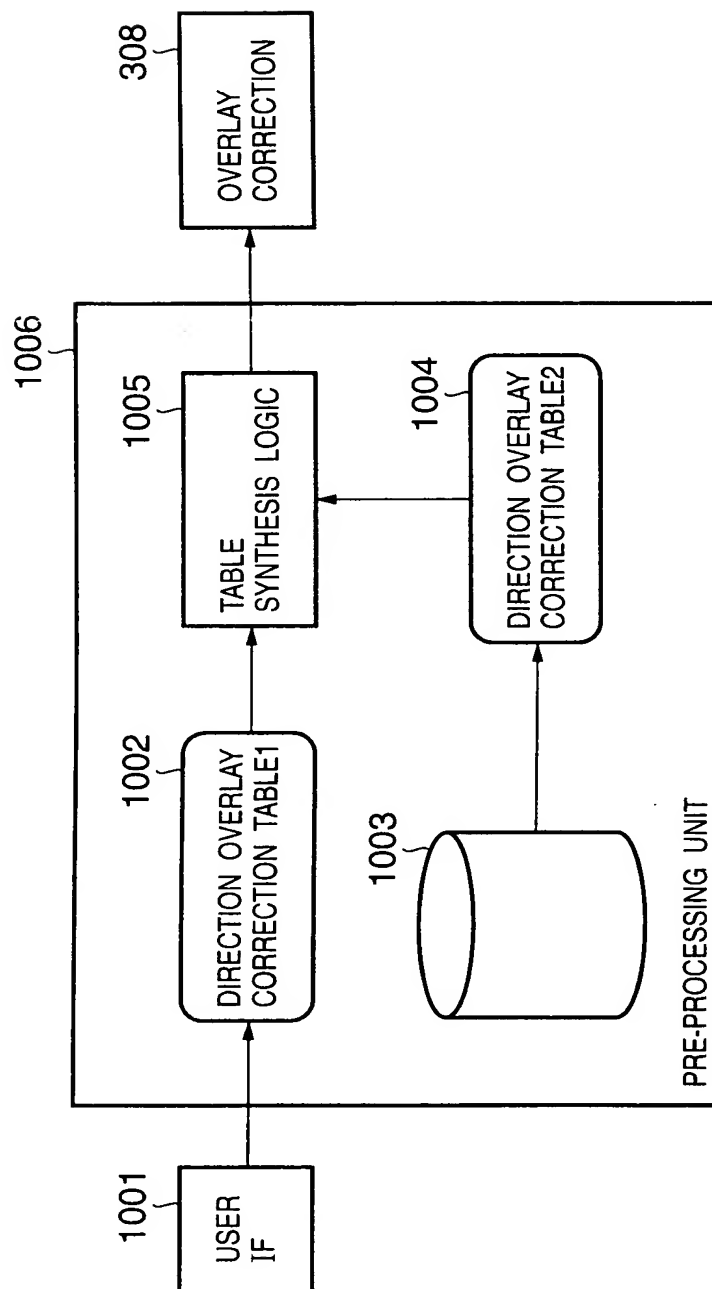


FIG. 11

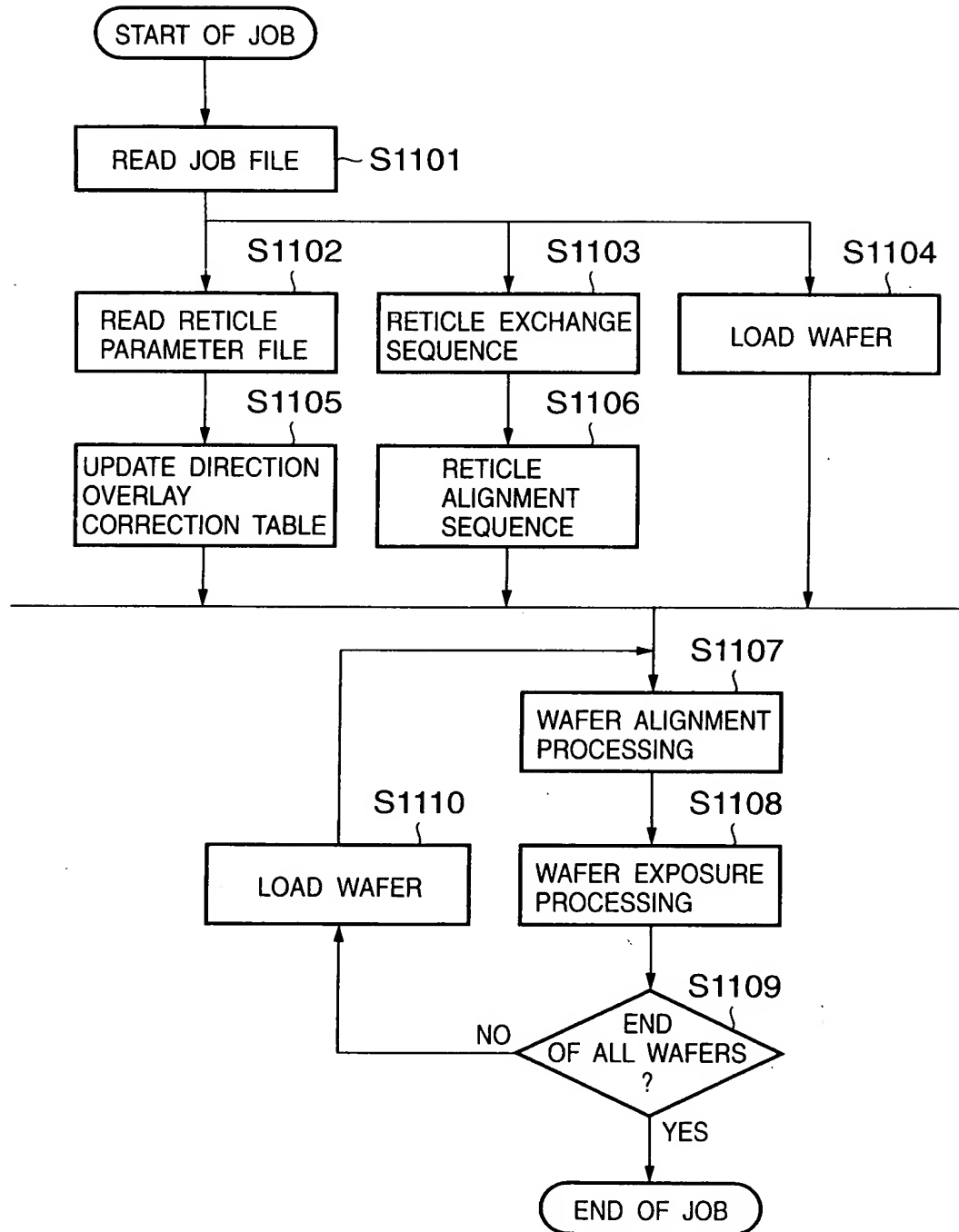
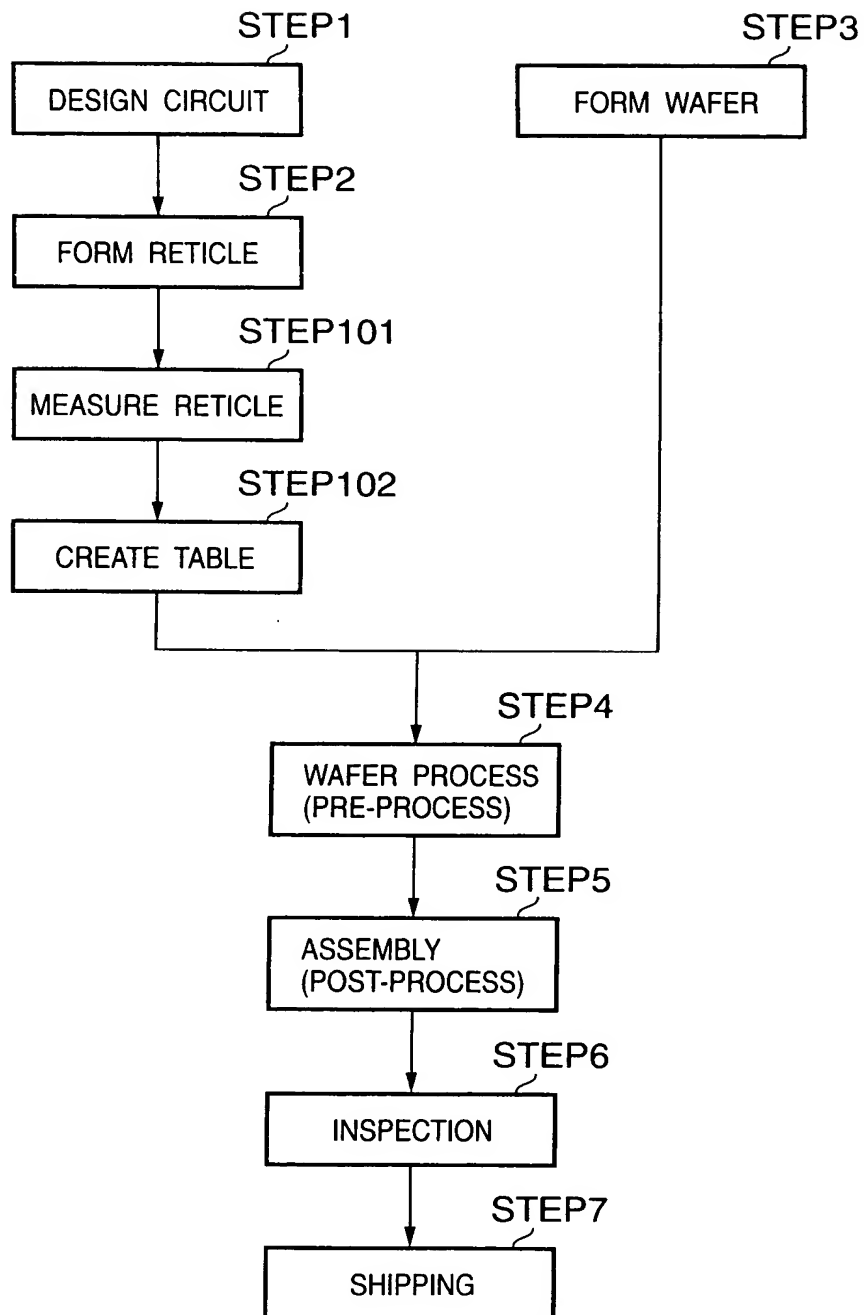


FIG. 12

SEMICONDUCTOR DEVICE MANUFACTURING FLOW

FIG. 13

